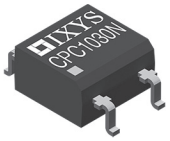
IXYS
INTEGRATED CIRCUITS DIVISION



CPC1030N
350V Normally-Open Single-Pole 4-Pin SOP OptoMOS® Relay

Parameter	Rating	Units
Blocking Voltage	350	V_P
Load Current	120	mA_{rms} / mA_{DC}
On-Resistance (max)	30	Ω

Features
- 1500V_{rms} Input/Output Isolation
- Small 4-Pin SOP Package
- Low Drive Power Requirements
- High Reliability
- Arc-Free With No Snubbing Circuits
- No EMI/RFI Generation
- Tape & Reel Version Available
- Flammability Rating UL 94 V-0

Applications
- Telecommunications
  - Telecom Switching
  - Tip/Ring Circuits
  - Modem Switching (Laptop, Notebook, Pocket Size)
  - Hook Switch
  - Dial Pulsing
  - Ground Start
  - Ringing Injection
- Instrumentation
- Multiplexers
- Data Acquisition
- Electronic Switching
- I/O Subsystems
- Meters (Watt-Hour, Water, Gas)
- Medical Equipment—Patient/Equipment Isolation
- Security
- Aerospace
- Industrial Controls

Description
The CPC1030N is a miniature single-pole, normally-open (1-Form-A) solid state relay in a 4-pin SOP package that employs optically coupled MOSFET technology to provide 1500V_{rms} of input to output isolation. The efficient MOSFET switches and photovoltaic die use IXYS Integrated Circuits Division's patented OptoMOS architecture while the optically coupled output is controlled by a highly efficient infrared LED.

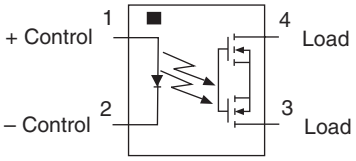
IXYS Integrated Circuits Division's state of the art double-molded vertical construction packaging makes the CPC1030N one of the world's smallest relays. It offers board space savings of at least 20% over the competitor's larger 4-pin SOP relay.

Approvals
- UL Recognized Component: File E76270
- CSA Certified Component: Certificate 1172007
- EN/IEC 60950-1 Certified Component: TUV Certificate B 13 12 82667 003

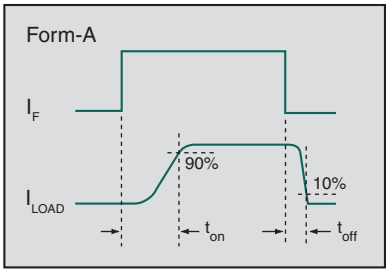
Ordering Information

Part #	Description
CPC1030N	4-Pin SOP (100/tube)
CPC1030NTR	4-Pin SOP (2000/reel)

Pin Configuration



Switching Characteristics of Normally-Open Devices



Absolute Maximum Ratings @ 25ºC

Parameter	Ratings	Units
Blocking Voltage	350	V_P
Reverse Input Voltage	5	V
Input Control Current	50	mA
Peak (10ms)	1	A
Input Power Dissipation [1]	70	mW
Total Power Dissipation [2]	400	mW
Isolation Voltage, Input to Output	1500	V_{rms}
Operational Temperature	-40 to +85	°C
Storage Temperature	-40 to +125	°C

[1] Derate linearly 1.33 mW / ºC
[2] Derate linearly 3.33 mW / ºC

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

Typical values are characteristic of the device at +25°C, and are the result of engineering evaluations. They are provided for information purposes only, and are not part of the manufacturing testing requirements.

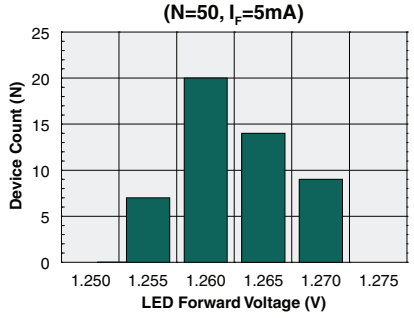
Electrical Characteristics @ 25ºC

Parameter	Conditions	Symbol	Min	Typ	Max	Units
Output Characteristics						
Load Current						
Continuous [1]	-	I_L			120	mA_{rms} / mA_{DC}
Peak	t=10ms	I_{LPK}	-	-	±350	mA_P
On-Resistance [2]	I_L=120mA	R_{ON}	-	19.5	30	Ω
Off-State Leakage Current	V_L=350V_P	I_{LEAK}	-	-	1	µA
Switching Speeds						
Turn-On	I_F=5mA, V_L=10V	t_{on}	-	-	2	ms
Turn-Off		t_{off}	-	-	1	
Output Capacitance	I_F=0mA, V_L=50V, f=1MHz	C_{OUT}	-	9	-	pF
Input Characteristics						
Input Control Current to Activate [3]	I_L=120mA	I_F	-	0.6	2	mA
Input Control Current to Deactivate	-	I_F	0.3	-	-	mA
Input Voltage Drop	I_F=5mA	V_F	0.9	1.2	1.5	V
Reverse Input Current	V_R=5V	I_R	-	-	10	µA
Input/Output Characteristics						
Capacitance Input to Output	V_{IO}=1V, f=1MHz	C_{IO}	-	1	-	pF

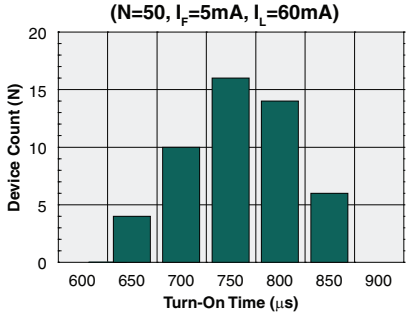
[1] Load current derates linearly from 120mA @ 25ºC to 60mA @85ºC.
[2] Measurement taken within 1 second of on-time.
[3] For applications requiring high temperature operation (greater than 60ºC) a minimum LED drive current of 4mA is recommended.

PERFORMANCE DATA*

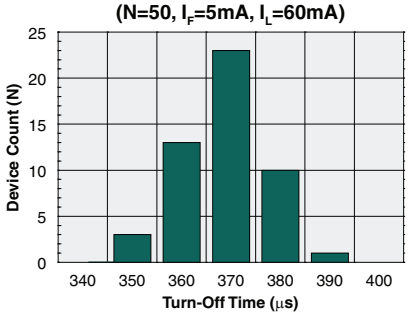
Typical LED Forward Voltage Drop
(N=50, I_F=5mA)



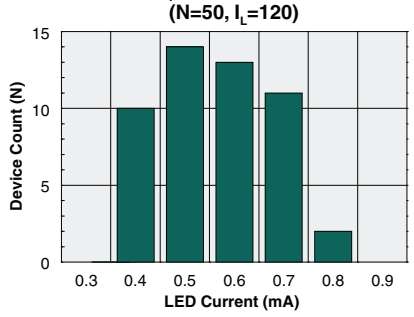
Typical Turn-On Time Distribution
(N=50, I_F=5mA, I_L=60mA)



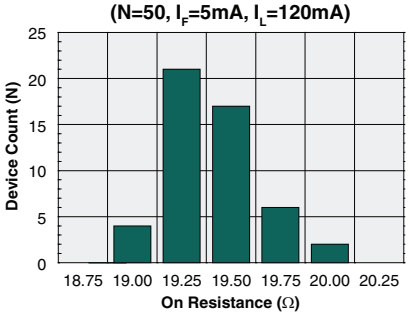
Typical Turn-Off Time Distribution
(N=50, I_F=5mA, I_L=60mA)



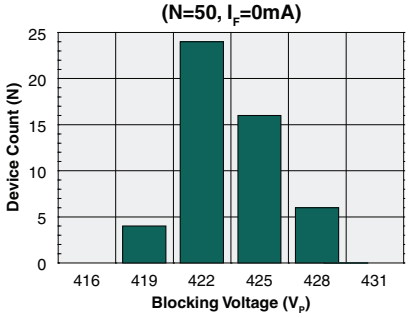
Typical I_F for Switch Operation
(N=50, I_L=120)



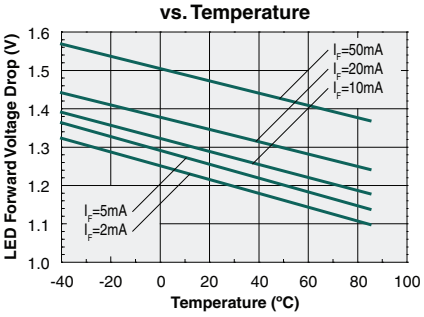
Typical On-Resistance Distribution
(N=50, I_F=5mA, I_L=120mA)



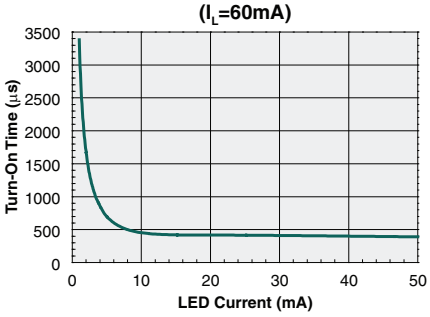
Typical Blocking Voltage Distribution
(N=50, I_F=0mA)



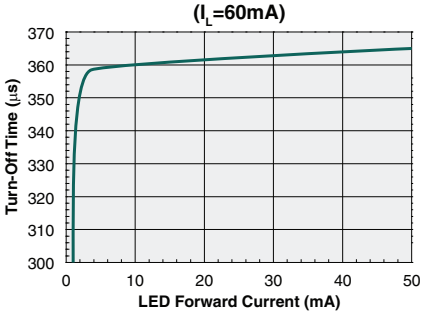
Typical LED Forward Voltage Drop
vs. Temperature



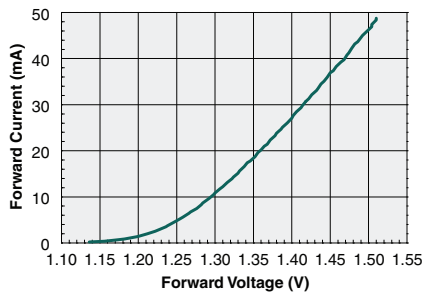
Typical Turn-On Time
vs. LED Forward Current
(I_L=60mA)



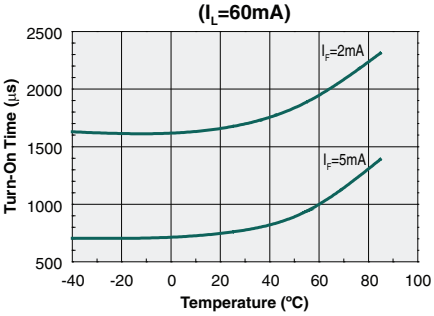
Typical Turn-Off Time
vs. LED Forward Current
(I_L=60mA)



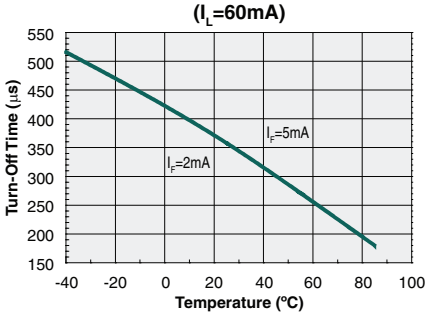
LED Forward Voltage
vs. LED Forward Current



Typical Turn-On Time
vs. Temperature
(I_L=60mA)



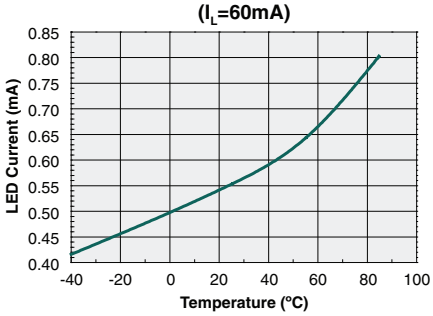
Typical Turn-Off Time
vs. Temperature
(I_L=60mA)



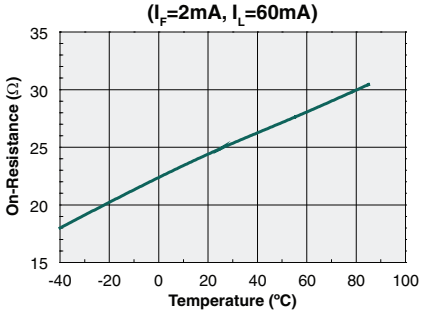
*Unless otherwise noted, data presented in these graphs is typical of device operation at 25°C.
For guaranteed parameters not indicated in the written specifications, please contact our application department.

PERFORMANCE DATA*

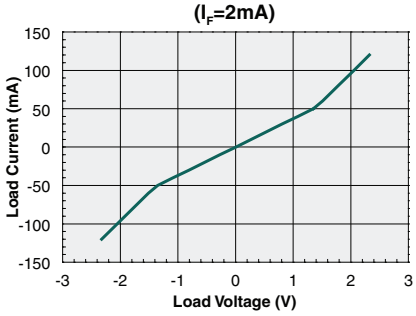
Typical I_F for Switch Operation vs. Temperature (I_L=60mA)



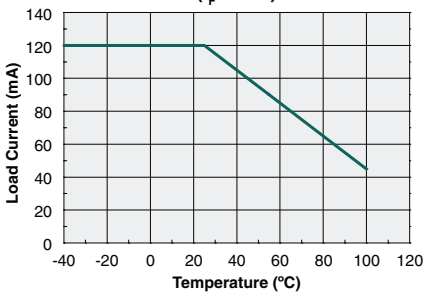
Typical On-Resistance vs. Temperature (I_F=2mA, I_L=60mA)



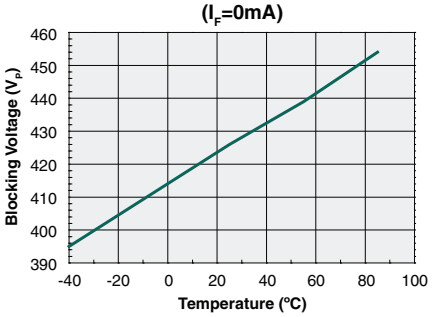
Typical Load Current vs. Load Voltage (I_F=2mA)



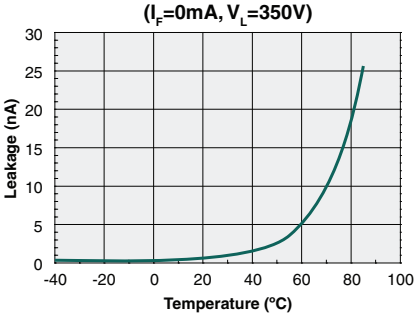
Maximum Load Current vs. Temperature (I_F=4mA)



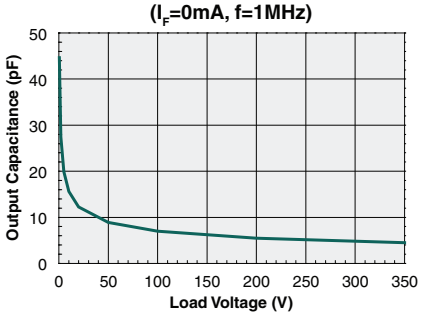
Typical Blocking Voltage vs. Temperature (I_F=0mA)



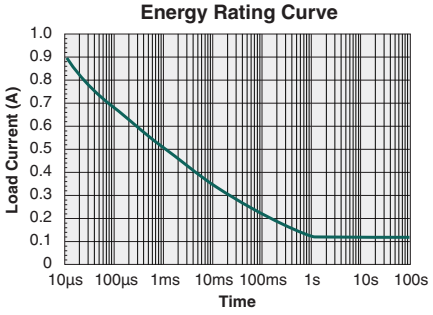
Typical Leakage vs. Temperature Measured Across Pins 3&4 (I_F=0mA, V_L=350V)



Output Capacitance vs. Load Voltage (I_F=0mA, f=1MHz)



Energy Rating Curve



*Unless otherwise noted, data presented in these graphs is typical of device operation at 25°C.
For guaranteed parameters not indicated in the written specifications, please contact our application department.

Manufacturing Information

Moisture Sensitivity

All plastic encapsulated semiconductor packages are susceptible to moisture ingression. IXYS Integrated Circuits Division classifies its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a Moisture Sensitivity Level (MSL) classification as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Classification
CPC1030N	MSL 3

ESD Sensitivity

This product is **ESD Sensitive**, and should be handled according to the industry standard **JESD-625**.

Soldering Profile

Provided in the table below is the Classification Temperature (T_C) of this product and the maximum dwell time the body temperature of this device may be (T_C - 5)ºC or greater. The classification temperature sets the Maximum Body Temperature allowed for this device during lead-free reflow processes. For through-hole devices, and any other processes, the guidelines of **J-STD-020** must be observed.

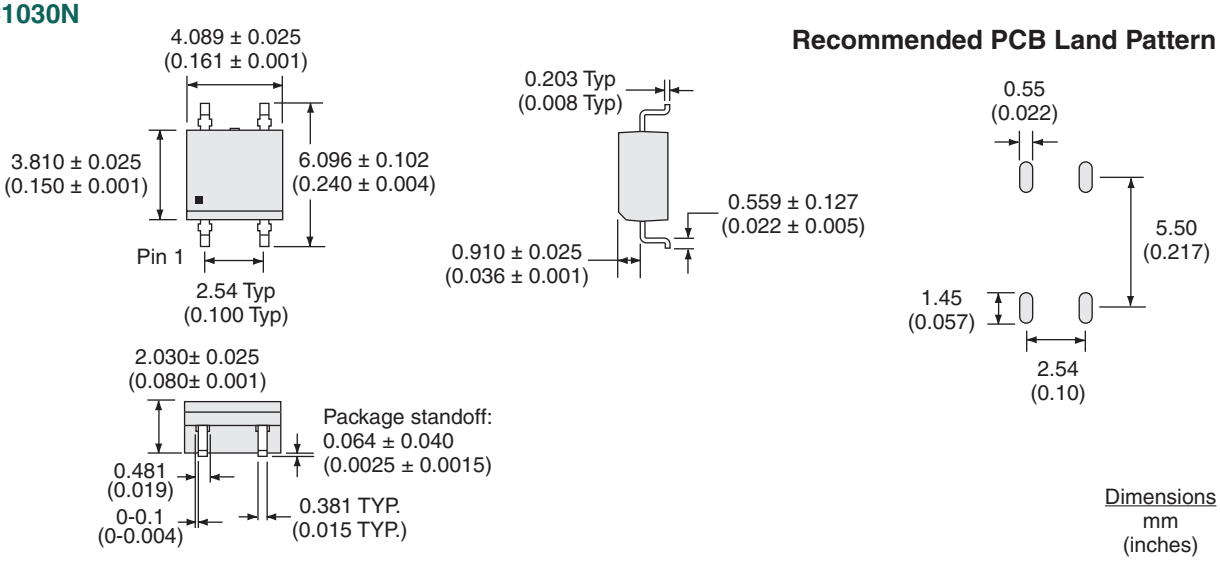
Device	Classification Temperature (T_c)	Dwell Time (t_p)	Max Reflow Cycles
CPC1030N	260ºC	30 seconds	3

Board Wash

IXYS Integrated Circuits Division recommends the use of no-clean flux formulations. Board washing to reduce or remove flux residue following the solder reflow process is acceptable provided proper precautions are taken to prevent damage to the device. These precautions include, but are not limited to: using a low pressure wash and providing a follow up bake cycle sufficient to remove any moisture trapped within the device due to the washing process. Due to the variability of the wash parameters used to clean the board, determination of the bake temperature and duration necessary to remove the moisture trapped within the package is the responsibility of the user (assembler). Cleaning or drying methods that employ ultrasonic energy may damage the device and should not be used. Additionally, the device must not be exposed to flux or solvents that are Chlorine- or Fluorine-based.

MECHANICAL DIMENSIONS

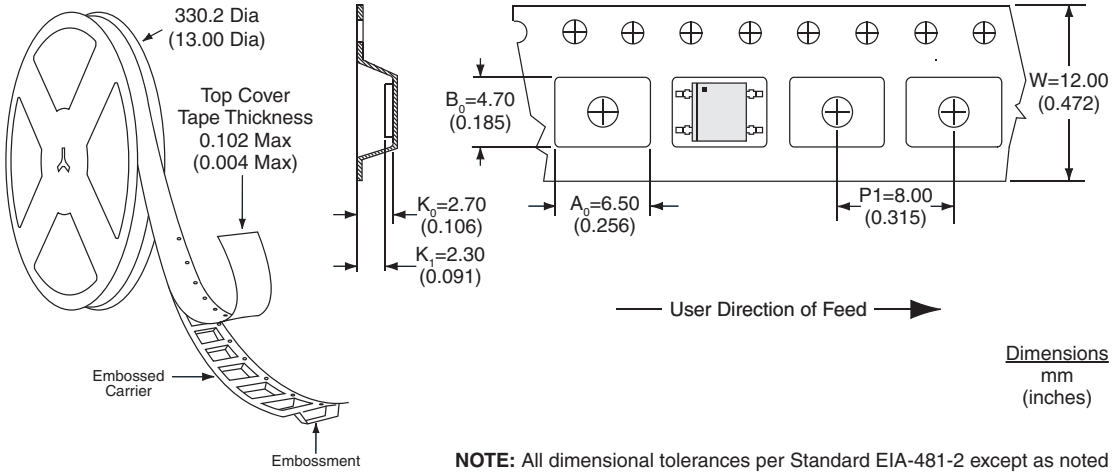
CPC1030N



Recommended PCB Land Pattern

Dimensions
mm
(inches)

CPC1030NTR Tape & Reel



Dimensions
mm
(inches)

NOTE: All dimensional tolerances per Standard EIA-481-2 except as noted

For additional information please visit our website at: www.ixysic.com

Specification: DS-CPC1030N-R17

1/30/2018